

# High-Z sensor materials on Medipix3RX

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ARDENT WORKSHOP 2014 - SCHWARZENBRUCK



### OUTLINE

- Summary of research activities
- Comparison between CdTe, CZT and Silicon bump bonded to Medipix3RX
  - Measurement setup
  - Calibration
  - Energy resolution
  - Flat field at 25 keV
  - Single pixel energy resolution
  - First look at MTF with CZT assemblies
  - Conclusions
  - Future work



	Timepix3
Pixel matrix	256 x 256
Pixel size	55 x 55 μm²
Technology	CMOS 130 nm
Measurement modes	<ul> <li>Simultaneous 10 bit TOT and 18 bit TOA</li> <li>18 bit TOA only</li> <li>10 bit PC and 14 bit integral TOT</li> </ul>
Readout type	<ul> <li>Data driven</li> <li>Frame based (both modes with zero suppression)</li> </ul>
Dead time	>475 ns (pulse processing + packet transfer)
Maximum count rate	85.3 Mhits / s
Minimum time resolution	1.56 ns
Power pulsing	Yes
Minimum threshold	~500 e-





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#### RESEARCH ACTIVITIES AND CONFERENCES SINCE THE LAST WORKSHOP

#### IEEE Conference in Seoul

- Dosimetry workshop: Measurement of backscattered radiation in a CT room using Dosepix
- RTSD: Spectral resolution and optimized threshold equalization of a charge summing hybrid pixel detector
- Beam time in Legnaro for Gempix and Timepix (with converters)
- Geant4Medipix: A simulation framework for hybrid pixel detectors
- First measurements with Timepix3
  - Oral presentation at the 16<sup>th</sup> iWoRID conference in Trieste, Italy
  - Co author on two poster presentations
- Characterization of CdTe and CZT bump bonded to Medipix3RX
  - Including 2 weeks in the X-ray lab in Sundsvall and a planned test beam at the ANKA synchrotron
- RQR, Medical beam quality measurements using Dosepix. In collaboration with IRA, Lausanne
  - Presented as a poster on the IRPA 2014 conference in Geneva



# LIST OF PUBLICATIONS

- E Frojdh, R Ballabriga, M Campbell, M Fiederle, E Hamann, T Koenig, X Llopart, D de Paiva Magalhaes and M Zuber, Count rate linearity and spectral response of the Medipix3RX chip coupled to a 300m silicon sensor under high flux conditions, JINST Vol 9, April 2014
- M De Gaspari, J Alozy, R Ballabriga, M Campbell, E Fröjdh, J Idarraga,c, S Kulis, X Llopart, T Poikela, P Valerio and W Wong, Design of the analog front-end for the Timepix3 and Smallpix hybrid pixel detectors in 130 nm CMOS technology, JINST Vol 9, January 2014
- Frojd, E.; Frojdh, C.; Gimenez, E.N.; Krapohl, D.; Maneuski, D.; Norlin, B.;O'Shea, V.; Wilhelm, H.; Tartoni, N.; Thungstrom, G.; Zain, R.M., Probing Defects in a Small Pixellated CdTe Sensor Using an Inclined Mono Energetic X-Ray Micro Beam, Nuclear Science, IEEE Transactions on , vol.60, no.4, pp.2864,2869, Aug. 2013
- 4. R Ballabriga, J Alozy, G Blaj, M Campbell, M Fiederle, E Frojdh, E H M Heijne, X Llopart, M Pichotka, S Procz, L Tlustos andWWong, The Medipix3RX: a high resolution, zero dead-time pixel detector readout chip allowing spectroscopic imaging, JINST Vol 8, February 2013
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- 8. E. Fröjdh, B. Norlin, G. Thungström and C. Fröjdh X-ray absorption and charge transport in a pixellated CdTe detector with single photon processing readout, JINST Vol 6, February 2011
- 9. E. Fröjdh, A. Fröjdh, B. Norlin, C. Fröjdh, Spectral response of a silicon detector with 220m pixel size bonded to MEDIPIX2, NIMA:, Volume 633, Supplement 1, May 2011, Pages S125-S127
- 10. A. Fröjdh, E. Fröjdh, G. Thungström, C. Fröjdh, B. Norlin, Processing and characterization of a MEDIPIX2-compatible silicon sensor with 220m pixel size, NIMA, Volume 633, Supplement 1, May 2011, Pages. S78-S80,





# MOTIVATION FOR HIGH-Z MATERIALS



Absorption in 1 mm



FLUORESCENCE IN HIGH-Z MATERIALS									
Mean free path of fluorescence photon $[\mu m]$ Fluorescence yield $[\%]$									
Energy fluorescence photons [keV]									
z									
Material	N	$K_1$	$L_2$	$L_3$	$K_{\alpha 1}$	$K_{\alpha 2}$	$d_{\alpha 1}$	$d_{\alpha 2}$	$\eta[\%]$
Si	14	1.84	0.10	0.10	1.74	1.74	11.86	11.86	4.1
GaAs									
Ga, $48.20\%$	31	10.36	1.14	1.11	9.25	9.22	40.62	40.28	50.5
As, $51.80\%$	33	11.87	1.36	1.32	10.54	10.50	15.62	15.47	56.6
CdTe									
Cd, $46.84\%$	48	26.71	3.73	3.53	23.17	22.98	113.20	110.75	83.6
Te, $53.16\%$	52	31.81	4.61	4.34	27.47	27.20	59.32	57.85	87.3

The mean free path of the fluorescence photons is in the same order of magnitude as the pixel pitch

The fluorescence yield increases with the atomic number



### **MEDIPIX3RX**

- 256x256 pixels
- 55x55 um pitch
- Charge summing over dynamically allocated 2x2 pixel clusters
- 2x12bit counters and 2 thresholds per pixel
- 5 bit Threshold adjustment dac
- Highly configurable
  - 4 different gain modes
  - Single pixel or charge summing
  - Electron or hole collection
  - Intrinsic 55um pixel pitch or 110um pixel pitch using eight thresholds per pixel





Layout of 2x2 pixels



### **MEDIPIX3: CHARGE SUMMING**

#### 2MM TICK CdTe SENSOR 110UM PITCH





### **SENSORS**

	W109_C3	W1127_I6	W146_F9	W146_F10
Material	Silicon (n-on- p)	CdTe	CZT	CZT
Pixel size	55 um	110 um	110 um	110 um
Thickness	200 um	2 mm	2 mm	2 mm
Bias voltage	-60 V	-600V	-600V	-600V
Leakage current	< 2 uA	~4uA	< 0.5 uA	< 0.5 uA



**CALIBRATION – CSM** 1. VERIFICATION OF INPUT SPECTRUM



Amptek X-123CdTe Spectrometer



### **CALIBRATION – CSM** 2. FIT OF THE PEAK WITH TWO GAUSSIANS



Same sigma is used and the ratio between the k $\alpha$  and k $\beta$  peak is 0.22 for CZT and 0.16 for Silicon

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# **CALIBRATION – CSM**

#### **3. LINEAR FIT TO THE FOUR PEAK POSITIONS**





# **CALIBRATION – SPM**

#### 2. FITTING THE DIFFERENTIATED SPECTRUM WITH AN ERROR FUNCTION





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## **ENERGY RESOLUTION**

CSM, FWHM (keV)

	15.7	17.5	22.2	25.3
W109_C3 (Silicon)	2.25	2.26	2.55	2.65
W109_C3 (Silicon)*	2.25	2.31	2.34	2.43
W146_F9 (CZT)	3.73	3.97	4.31	4.51
W146_F10 (CZT)	4.32	4.44	5.17	5.24
W146_F10* (CZT)	4.67	4.91	5.15	5.32
W1127_I6 (CdTe)	3.12	3.09	3.53	3.69

\*HGM/High Equalized at 7000e--



#### DEPENDENCE ON BIAS VOLTAGE 25keV Sn FLUORESCENCE



Both materials show similar characteristics



# **FLAT FIELD**

- Fluorescence from Sn (25keV)
- Threshold at ~ 9 keV
- Threshold mismatch should have only a small influence on the number of counts.
- HGM, Moderate





### **FLAT FIELD**



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Note! Poisson limit  $\sigma \sim 110$ 

### **FLAT FIELD**



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Note! Poisson limit  $\sigma \sim 110$ 



Note! Poisson limit  $\sigma \sim 110$ 

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### **PEAK POSITION (CZT)** CSM, 25keV Sn FLUORESCENCE



 $\sigma$  = 2.24 TH1 step  $\sigma$  = 1.32 keV



### ENERGY RESOLUTION (CZT) CSM, 25keV Sn FLUORESCENCE



 $\mu$  = 3.89 keV  $\sigma$  = 0.97 keV

Note: The increased noise on the right side is minimized in Medipix3RXv2 respin



### PEAK POSITION (CdTe) CSM, 25keV Sn FLUORESCENCE



 $\sigma$  = 1.93 TH1 step  $\sigma$  = 1.12 keV



### ENERGY RESOLUTION (CdTe) CSM, 25keV Sn FLUORESCENCE



 $\mu$  = 3.56 keV  $\sigma$  = 0.73 keV

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# **PEAK/EDGE POSITION (CZT)**

#### SPM, 25keV Sn FLUORESCENCE





### PEAK/EDGE POSITION (CZT) SPM, 25keV Sn FLUORESCENCE



 $\sigma$  = 5.36 TH0 step (*Note! the gain is ~2x of TH1*)  $\sigma$  = 1.63 keV



### PEAK/EDGE POSITION (CZT) SPM, 25keV Sn FLUORESCENCE





#### Counts, 25keV, CSM



### **NOISE VS. TP EQUALIZATION**



No improvement In energy resolution for CZT



### **NOISE VS. TP EQUALIZATION**



No improvement In energy resolution for CdTe, even a slight degradation.



## LINE IMAGES, CZT

W146\_F0, CSM



Measurements using a tungsten slit reveals displacement of charge. This is believed to be the main cause of the count rate differences in the sensor.



### **SLANTED EDGE MTF**



1.0 0.8 0.6 0.4 0.2 0.0 -300 -200 -100 0 100 200 300 x disance ( $\mu$ m)

**Oversampled Edge Response** 

Tungsten edge 120kVp + 3mm Al



### **SLANTED EDGE MTF**





Tungsten edge 120kVp + 3mm Al



### CONCLUSIONS

- Both CdTe and CZT displays good energy resolution across the sensor
- The lack of improvement in energy resolution using a test pulse calibration suggest gain differences induced by the sensor for both CdTe and CZT
- Large count rate differences are observed in the CZT sensors, probably caused by charge displacement due to an inhomogeneous electrical field
- Imagining performance is greatly affected by this charge displacement



# **FUTURE WORK**

- Long term stability and polarization
- Improvements in the equalization procedure.
  - Precise TP measurement.
  - Ideas to use radiation
- Low energy response (3-8 keV)
- High energy response (120-662 keV)
- NPS, MTF, DQE



#### **ACKNOWLEDGEMENTS:**

This research project has been partly supported by the Marie Curie Initial Training Network Fellowship of the European Community's Seventh Framework Programme under Grant Agreement PITN-GA-4 2011-289198-ARDENT".

